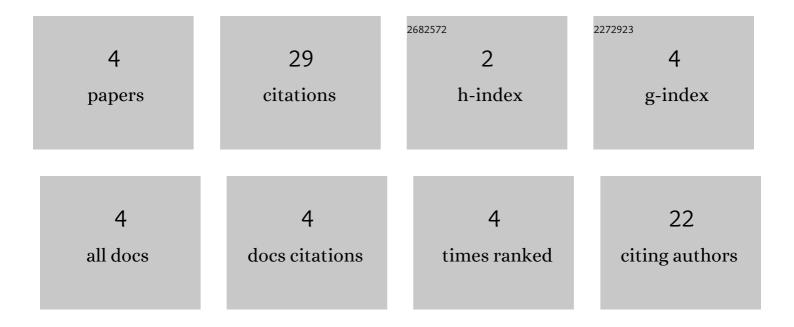
Anand Meled

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/11140215/publications.pdf Version: 2024-02-01



ANAND MELED

#	Article	IF	CITATIONS
1	Tribological, Thermal, and Kinetic Characterization of 300-mm Copper Chemical Mechanical Planarization Process. Japanese Journal of Applied Physics, 2011, 50, 05EC02.	1.5	15
2	Analyses of Diamond Disk Substrate Wear and Diamond Microwear in Copper Chemical Mechanical Planarization Process. Journal of the Electrochemical Society, 2010, 157, H250.	2.9	11
3	Pad Wear Analysis during Interlayer Dielectric Chemical Mechanical Planarization. ECS Journal of Solid State Science and Technology, 2012, 1, N103-N105.	1.8	2
4	Slurry-Induced Pad Wear Rate in Chemical Mechanical Planarization. Electrochemical and Solid-State Letters, 2010, 13, H52.	2.2	1